









Release Date: 30 March 2015 Version: A1.0

# PRODUCT DATASHEET



- ► PLCC2 SMD
- ➤ 2835 0.8t Series
- ➤ Warm White (2800K)

N0W00S71





# **2835 0.8t Series**





#### **FEATURES:**

Package: PLCC2 White SMD Package

Forward Current: 150mA Forward Voltage (typ.): 3.2V

Luminous Flux (typ.): 47lm@150mA

Colour: Warm White

Colour Temperature (CCT): 2800K

Viewing angle: 120°

**Materials:** 

Die: InGaN

Resin: Silicon (Yellow Diffused)

L/T Finish: Ag plated

Operating Temperature: -40~+80°C

Storage Temperature: -40~+100°C

**Grouping parameters:** Forward Voltage

Luminous Flux

**CIE Chromaticity** 

Soldering methods: Reflow Soldering

Preconditioning: MSL3 according to JEDEC

Packing: 8mm tape with 4000/reel, ø180mm (7")

#### **APPLICATIONS:**

- **General Lighting**
- Portable Lighting
- Commercial Lighting
- **Indoor Lighting**
- Backlight for LCD



### **CHARACTERISTICS:**

## Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I <sub>F</sub>	180	mA
Pulse Forward Current (Duty 1/10, width 0.1ms)	I <sub>PF</sub>	240	mA
Reverse Current @5V	I <sub>R</sub>	10	μΑ
Junction Temperature	Tj	110	°C
Operating Temperature	T <sub>OPR</sub>	-40~+80	°C
Storage Temperature	T <sub>STG</sub>	-40~+100	°C
Soldering Temperature	T <sub>SOL</sub>	260	°C
Colour Rendering Index	CRI	80 (typ.)	

### Electrical & Optical Characteristics (Ta=25°C)

Parameter	Cumbal	Symbol Values			Unit	Test	
Parameter	Зуппоп	Min.	Тур.	Max.	Offic	Condition	
Forward Voltage	$V_{F}$	2.8	3.2	3.4	V	I <sub>F</sub> =150mA	
Luminous Flux	Фу	40	47	55	lm	I <sub>F</sub> =150mA	
Chromaticity Coordinates	Х		0.4467			I <sub>F</sub> =150mA	
	Y		0.4076				
Colour Temperature	ССТ	2715	2870	3000	К	I <sub>F</sub> =150mA	
Viewing Angle	2θ <sub>1/2</sub>		120		deg	I <sub>F</sub> =150mA	

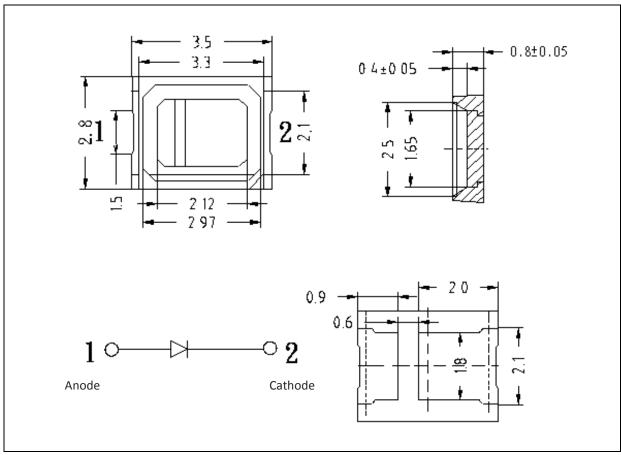
<sup>1.</sup> Luminous flux ( $\Phi_V$ )  $\pm 10\%$ , Forward Voltage ( $V_F$ )  $\pm 0.1V$ , Viewing angle( $2\theta_{1/2}$ )  $\pm 5\%$ , CRI $\pm 5$ 

<sup>2.</sup> IS standard testing



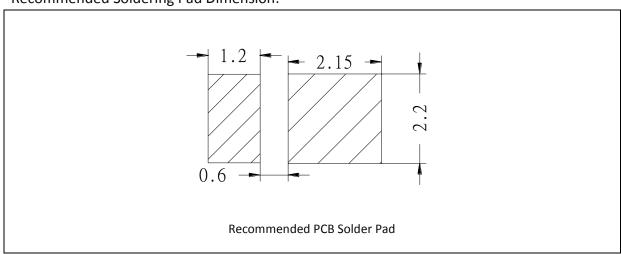
### **OUTLINE DIMENSION:**

### Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.13mm, unless otherwise noted.

# Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



### **BINNING GROUPS:**

# Forward Voltage Classifications (I<sub>F</sub> = 150mA):

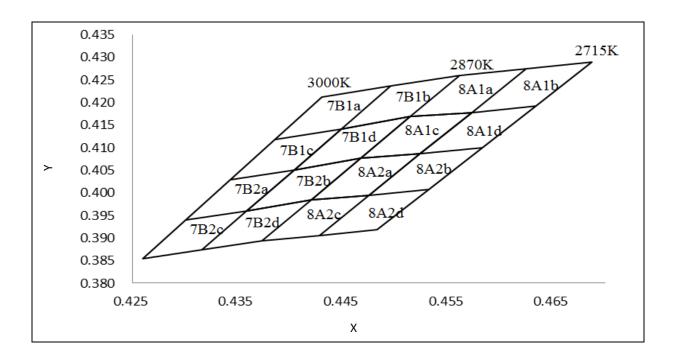
Code	Min.	Max.	Unit
В	2.8	2.9	
С	2.9	3.0	
D	3.0	3.1	V
E	3.1	3.2	V
F	3.2	3.3	
G	3.3	3.4	

# Luminous Flux Classifications ( $I_F = 150 \text{mA}$ ):

Code	Min.	Max.	Unit
23	40	45	
24	45	50	lm
25	50	55	



### **CIE CHROMATICITY DIAGRAM:**

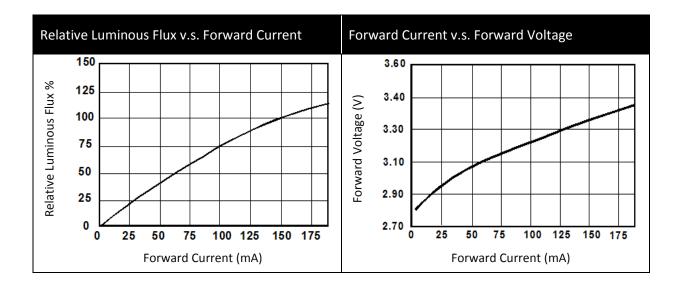


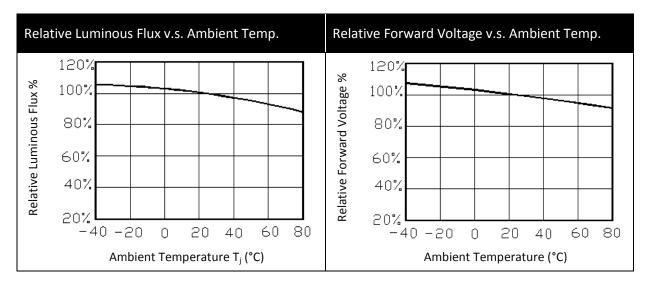
## Chromaticity Coordinates Classifications (I<sub>F</sub> = 150mA):

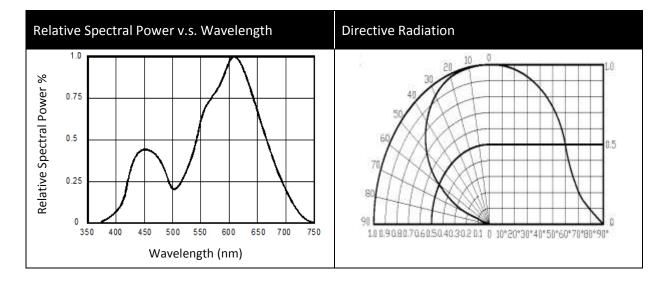
	-	1	2		3		4	
	Х	Υ	Х	Υ	Х	Υ	Х	Υ
7B1a	0.4496	0.4236	0.4431	0.4213	0.4386	0.4119	0.4449	0.4141
7B1b	0.4562	0.4260	0.4496	0.4236	0.4449	0.4141	0.4515	0.4168
7B1c	0.4449	0.4141	0.4386	0.4119	0.4343	0.4029	0.4404	0.4051
7B1d	0.4515	0.4168	0.4449	0.4141	0.4404	0.4051	0.4468	0.4077
7B2a	0.4404	0.4051	0.4343	0.4029	0.4301	0.3940	0.4359	0.3960
7B2b	0.4468	0.4077	0.4404	0.4051	0.4359	0.3960	0.4420	0.3985
7B2c	0.4359	0.3960	0.4301	0.3940	0.4260	0.3854	0.4317	0.3873
7b2d	0.4420	0.3985	0.4359	0.3960	0.4317	0.3873	0.4373	0.3893
8A1a	0.4625	0.4275	0.4562	0.4260	0.4515	0.4168	0.4573	0.4178
8A1b	0.4688	0.4290	0.4625	0.4275	0.4573	0.4178	0.4634	0.4193
8A1c	0.4573	0.4178	0.4515	0.4168	0.4468	0.4077	0.4524	0.4086
8A1d	0.4634	0.4193	0.4573	0.4178	0.4524	0.4086	0.4583	0.4100
8A2a	0.4524	0.4086	0.4468	0.4077	0.4420	0.3985	0.4475	0.3994
8A2b	0.4583	0.4100	0.4524	0.4086	0.4475	0.3994	0.4532	0.4008
8A2c	0.4475	0.3994	0.4420	0.3985	0.4373	0.3893	0.4428	0.3906
8A2d	0.4532	0.4008	0.4475	0.3994	0.4428	0.3906	0.4483	0.3919



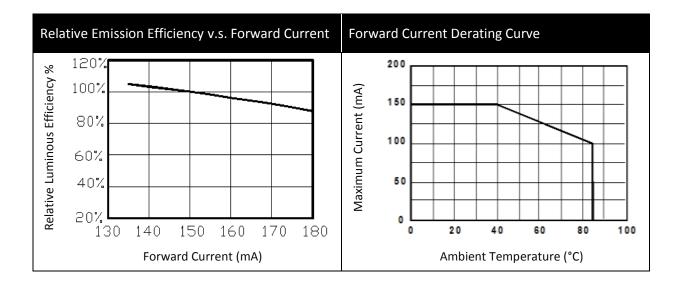
#### **ELECTRO-OPTICAL CHARACTERISTICS:**







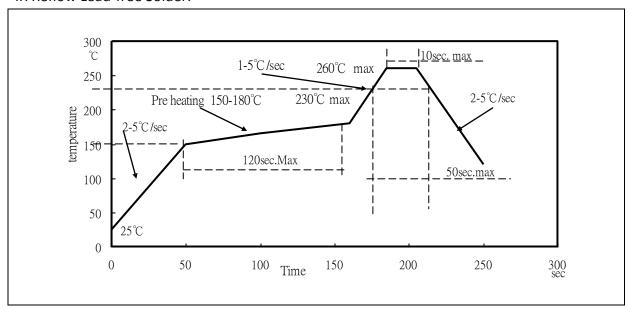






#### **RECOMMENDED SOLDERING PROFILE:**

#### IR Reflow Lead-free Solder:



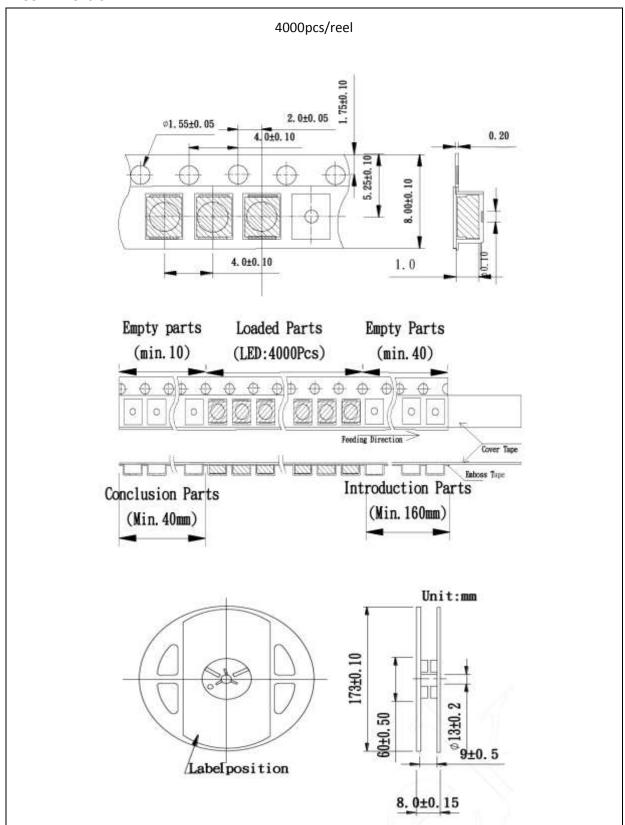
#### Note:

- 1. Maximum reflow soldering: 3 times.
- 2. Recommended reflow temperature: 240°C. Maximum soldering temperature should be limited to 260°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



### **PACKING SPECIFICATION:**

#### Reel Dimension:





#### **PRECAUTIONS OF USE:**

#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

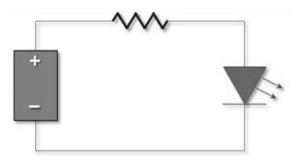
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.</li>
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

#### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



## **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	30/03/2015	Datasheet set-up.